Call for Papers

ADMETA*Plus* 2020

ADMETA

ADVANCED METALIZATION

Advanced Metallization Conference 2020: 30th Asian Session

October 14 - 16, 2020

Tokyo Institute of Technology, Tokyo Tech Front (Ookayama), Tokyo

Sponsorship by ADMETA Committee

Co-sponsorship by the Japan Society of Applied Physics

The *ADMETA*Plus is heading for its 30th historical meeting and has a long record of important contributions to practical progress for advanced MPU and various memory devices. In recent years, the importance of interconnect technology for realizing low resistance, large integration, rich functionality, low cost, and high reliability has increased in various device application fields beyond silicon electronics. This conference will focus on interconnects technology and science related to materials, processes, device design, assembly, equipment, cost performance, and characterization. ADMETA will conduct lively discussions with academic, government, and industrial researchers and engineers on the interconnect technologies required for newly developed devices.

*ADMETA*Plus 2020 Special Chairperson, Prof. Kazuya Masu (Tokyo Institute of Technology)
General Chair, Kazuyoshi Maekawa (Renesas Electronics Corporation)

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★Conference Topics of Interest

Integration: Interconnection Structure and Performance, Parasitic Capacitance, Reliability Technology, Testing and Analysis

Reliability Science and Failure Analysis: EM, SIV, TDDB, Defect Detection and Analysis, Failure Mechanism and Modeling

Metallization: PVD, CVD, ALD, Plating, Barrier Metal, New Material, Alloy, Supercritical Fluid, Reflow

Low-k Dielectric: CVD, ALD, SOD, Film Properties, New Materials, Dielectric Structures (Air Gap), Metrology, etc.

CMP: Planarization Technology, Slurry, Pad, Dress, End Point Detection, Cleaning, Anti-corrosive Technology, etc.

Contact: Silicide, Interface, Solid Phase Reaction, Shallow Junction, Crystal Properties, Electron Properties, Carrier Transport, etc.

MEMS/RF: Interconnection Structure and Materials, Packaging, Fabrication Process Technology, Device Design, etc.

Emerging Technology: Active Wiring, Power Electronics, Silicon Photonics, Flexible Electronics, Energy Harvesting, etc.

Backend Device Technology: Tech. for Embedding Devices (MRAM, PCRAM, ReRAM, DRAM etc.), Materials and Processing of Magnetics, Phase-Change and Resistive-Change Devices, Electrode, Metallization, etc.

Nano Carbon: Graphene, CNT, Deposition, Integration, Electrical Characteristics, Reliability, Evaluation, Analysis, etc.

3D and Packaging: TSV, TMV, Stacking Method (CoW, WoW), Thinning, Planarization, Bonding, Bump, Stress and Thermal Analysis, Sealing, Cooling, Reliability.

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★ To Apply:

Prepare an abstract per the directions below and submit it to the ADMETA*Plus* 2020 Secretariat;

A4 format, up to 2 pages, figures and tables are recommended but not required,

Oral [15 min. talk & 5 min. QA] or Poster [90 min.],

Abstracts are due June 26, 2020.

Prospective authors must submit a PDF file up to 2 pages with necessary figures and tables. Send the PDF file of the manuscript, the subject of your paper (please choose from the Conference Topics of Interest), and desired presentation style (Oral or Poster) to the secretariat office via e-mail. On the abstract, please indicate the author to whom correspondence should be addressed, and include mailing and e-mail addresses. A template of abstract can be downloaded from the ADMETA*Plus* 2020 website. Notification of acceptance will be made to the authors by August 28, 2020. Upon notification, authors will be requested to confirm their participation in the conference.

The accepted abstracts will be included in the conference proceedings (paper and/or CD-ROM), which the participants will receive on site at the registration desk of ADMETA*Plus* 2020. Pre-registered participants will also be able to download the accepted abstracts from the ADMETA*Plus* 2020 webpage after Oct. 7, 2020.

QRcord toURL

http://www.admeta.org/

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ADVANCED METALIZATION

★ Special Issue of JJAP

Authors with papers presented at ADMETA^{Plus} 2020 are encouraged to submit their original manuscripts to a Special Issue of the Japanese Journal of Applied Physics (JJAP) dedicated to the ADMETA^{Plus} 2020. The deadline for submitting the Special Issue is scheduled around November 2020. The manuscript will be reviewed based on the JJAP standard for an original paper. JJAP Special Issues are accepting regular papers (RP), brief notes (BN), and reviews (RV), and will be published in July, 2021.

★ Reminder

As the papers of the Special Issue will be the original papers, please be careful not to post the same contents to any other journals.

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Conference Information: Oct.15-16, 2020 (in English)

★ Preliminary list of Planary Speakers:

★ Organized Sessions

1) Emerging Technologies (STT-MRAM, ReRAM)
2) Advanced Metallization
3) Advanced Integration and Process

★ General Sessions

1) Thin films and Dielectrics
2) CMP and Cleaning
3) Next Generation Interconnect (Carbon, Optical Interconnects etc.)
4) 3D Device, TSV and Packaging

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Tutorial Information: Oct.14, 2020 (in Japanese)

★ Preliminary list of Tutorial Lecturers include:

1) Metallization
2) 3D Flash Memory
3) ALD
4) Semiconductor Market Trend
5) Interconnect Conference Trend
6) Lithography
7) CMP
8) 3D CMOS image sensor

*Full list of the invited speakers and tutorial lecturers will be announced later.

****Official language of the Tutorial Lecturers is Japanese.**

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★ Contact: ADMETA^{Plus} 2020 Secretariat

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